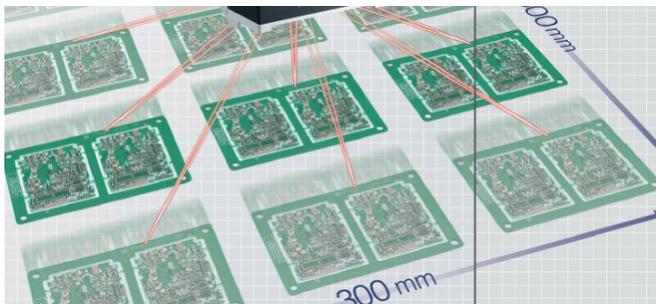


HIGH PRECISION WAFER/CHIP MARKER & SORTER

QM's Dynamics Marker (DM-200 & DM-300) series CO₂ laser marking / scribing/ sorting system is equipped with a 3-axis simultaneous laser control system that creates precise marking and improves the accuracy of marks on large flat surfaces.

The utilization of non-contact edge grip end effector and edge-grip aligner with our proprietary SoftTouch gripping mechanism ensures damage and contamination free wafer transfers.

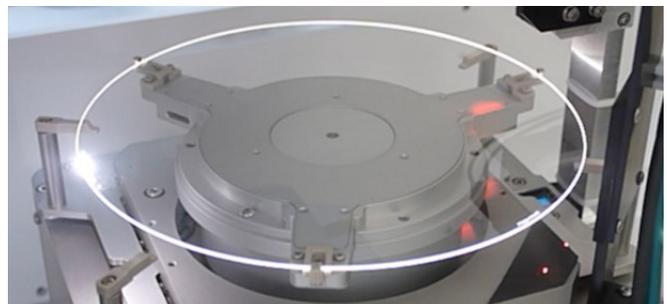
The IEG Aligner with buffer allows you to achieve significantly higher throughput. A combination of high precise laser control and wafer alignment mechanism minimize area reserved for marking, consequently, permit more dies on the wafer.



Marking coverage
300mm x 300 mm

FEATURE

- For 200 or 300mm, thin or thick, silicon, glass or compound substrates
- Contactless handling
 - contamination free
- High precision marking
 - less area needed
- Chip ID marking
 - uniform spot size covers 300mm x 30mm wide area
- For fine-line standard or custom font, image, bar code/2D matrix & scribing
- Highly configurable platform, up to 6 ports/200mm, 4 ports/300mm for wafer sorting



Alignment repeatability 10 μ m centering/ 0.006° angular; marking speed - 6000 mm/s max; resolution 5 μ m

STANDARD CONFIGURATION OPTION

- * 200mm or 300mm Si, glass & compound wafers
- * Manual door
- * Up to 6 ports/200mm, 4 ports/300mm
- * 1 robot with SoftTouchedge grip end effector
- * 1 SoftTouchedge grip aligner
- * Detect carrier presence
- * Detect empty, double or cross slotted wafers
- * Manual or S/W driven sorting
- * Bilingual GUI (English/Chinese)
- * SECS/GEM protocol compliant

- * Wafer protrusion detection
- * Flipping for both side marking
- * Aligner with buffer
- * Aligner supports thin wafers
- * Auto door
- * SMIF/FOUP/coin stack shipper

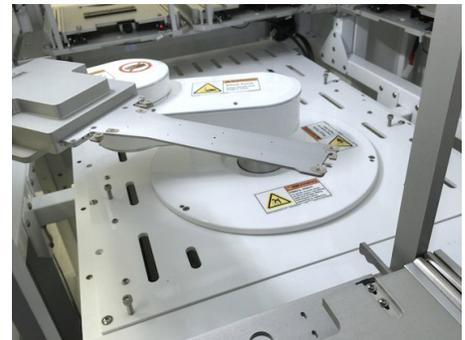
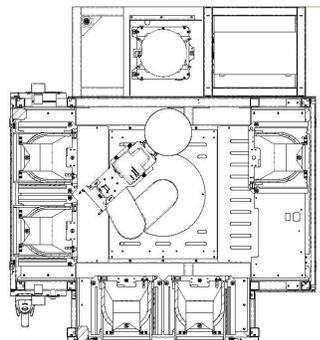
- * FFU/Ionizer/Exhaust
- * ID reading: OCR supports for top, bottom, or both. Most common codes supported
- * Carrier ID (bar code/RFID)
- * SECS/GEM communication



SPECIFICATION (Laser device to customer specification upon request)

Marking area	300 x 300 mm	Scribing/cutting	Line, dot, circle, oval etc.
Working distance	300 ± 21mm	Wavelength	10.6 μm
Marking resolution	5 μm	Laser type	CO ₂ laser, class 4 laser
Scan speed	6000 mm/s max	Product	
Character type	Std or custom font, bar code, 2D-code, GS1 DataBar, bmp/jpg image	Supply voltage	100 to 120 VAC / 200 to 240 VAC 50 / 60 Hz 1500 VA

SAMPLE 8" PLATFORM LAYOUT (Approxi. 1420 L x 1300 W x 1900 H mm)



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